ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES® International and Pan-	C. Bannockł	burn, Illinois, A	ll rights reserved utions.	under both	This docum level parts, t	ent is a declarat	ion of the su	ibstances v s all lower	within the manufactu level materials for v	rer listed i which the r	tem. Note: nanufacture	if the item is an as r has engineering	sembly with low responsibility.	
			Form Type Distribute	*	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information				
Supplier Information														
Company name* Company u			nique ID			Unique ID Authority				Respon	Response Date*			
nsemi											2023-06-08			
Contact Name	t Name Title - Contact					Phone - Contact*				Email -	Email - Contact*			
roduct-Env-Stewards Product Enviro Compliance			ro Compliance			NA			Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Representative				Phone - Representative*				Email - Representative*						
Product-Env-Stewards Product Envir			iro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	M	Ianufacturing Site		Weight*	UOM	Unit Type	
	NCP161	P161AFCT290T2G CSP LDO 450mA, A		A, Active Disch	arge	2023-06-08	CNQ		NQ		0.2662	mg	Each	
Aanufacturing Proccess Informat	ion													
Terminal Plating / Grid Array Mat	terial 7	al Terminal Base Alloy J-S		J-STD-020 MSI	L Rating	Peak Process Body Temp		emperature	ature Max Time at Peak Ter		ture Num	ber of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30	secor	nds 3				
omments														
vel 1 - maximum time at peak temperatu	re during so	Idering is 10-3	0 seconds											
or more information regarding material o	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select select a RoHS exemption, if applic sigma range of distribution unless	cable [E] enter the weigh	, Requester or Supplier) [B It of the substance or the Pl] select the substa PM concentration	ance category (JIG or Requester) or [F] Optionally enter the positive (-	enter a value (Supplier). [C] selec -) and negative (-) tolerance in per	t the substance (JI cent (Note: percen	G) or enter the substant tolerance values are	nce and CAS (Other). [D] expected to cover a 3
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Bump	0.02444	mg	Supplier	Tin (Sn)	7440-31-5		0.0244	mg
Die	0.21966	mg	Supplier	Silicon (Si)	7440-21-3		0.2197	mg
Protection coat	0.0059	mg		Polyimide	proprietary data		0.0059	mg
RDL Sputter	4.3E-4	mg	Supplier	Titanium (Ti)	7440-32-6		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0004	mg
UBM/RDL PCu	0.01527	mg	Supplier	Copper (Cu)	7440-50-8		0.0153	mg
UBM Sputter	5.0E-4	mg	Supplier	Titanium (Ti)	7440-32-6		0.0001	mg
			Supplier	Copper (Cu)	7440-50-8		0.0004	mg